



**Highlights**

- Electronics-grade pure silica-based nanoparticles, designed for silicon wafer stock polishing
- Broad particle size distribution provides unique balance of rate and finish
- Engineered products stable across a broad pH range

Colloidal silica slurry

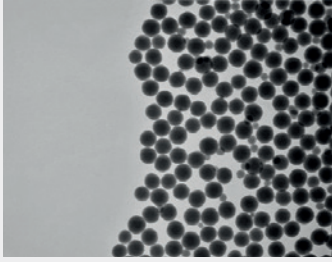
**NALCO™ 2358**

NALCO™ 2358 is a colloidal silica polishing slurry specifically formulated as a next generation replacement to the NALCO™ 2350. It contains lower metals than 2350, and typically yields a 10 – 15 % higher removal rate. This is especially effective on silicon surfaces due to temperature sensitive amine which activates at 40 degrees Celsius.

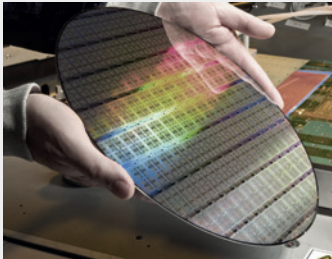
**Typical applications**

Silicon

Properties and similar products	Base material	Particle size [µm]	pH value	Solids content [%]	Specific gravity
NALCO™ 2329	Colloidal silica	0.08	8.4	40.0	1.29
NALCO™ 2350	Colloidal silica	0.06	11.0	50.0	1.39
NALCO™ 2358	Colloidal silica	0.07	12.0	28.0	1.19
NALCO™ 2360	Colloidal silica	0.06	8.5	50.0	1.39
NALCO™ 2371	Colloidal silica	0.07	11.8	28.0	1.19
NALCO™ 2398	Colloidal silica	0.09	11.8	28.0	1.19



NALCO™ 2358 is an excellent colloidal silica designed for stock removal processes.



NALCO™ 2358 is most commonly used to polish, prime, and reclaim silicon wafers.



Pureon offers a wide range of customized solutions. More information can be found on [www.pureon.com/products/overview](http://www.pureon.com/products/overview)

**Product specifications**

Base material ..... Colloidal Silica  
Shelf life ..... 24 months

**Order information**

Packing ..... 5 gal jugs, and 55 gal drums.  
264 gal tote, and 330 gal tote.  
Other sizes available upon request.  
Unit of measure ..... Gallon [gal]

**Application recommendations**

Handling ..... Storage tanks and distribution piping should be constructed of engineering plastic, such as polyethylene, polypropylene, or PTFE. Materials such as aluminum, copper, brass, and PVC should be avoided. Avoid leaving slurry containers open for extended periods of time. Leaving containers open may result in drying which can cause wafer scratching.

Storage ..... Storage outside of the recommended conditions may result in irreversible product degradation. Products can be stored up to the expiration date between the temperatures range of 0 °C – 45 °C (32 °F – 113 °F). Avoid prolonged exposure at temperatures at either extreme. In all cases the products should be allowed to return to a room temperature prior to use. All shipments include temperature indicators to monitor shipping conditions.

Disposal ..... Dispose of in accordance with all applicable local regulations.

Pureon is an Authorized distributor of NALCO™.

**Contact**

**Pureon**  
sales@pureon.com  
www.pureon.com/sales-contacts